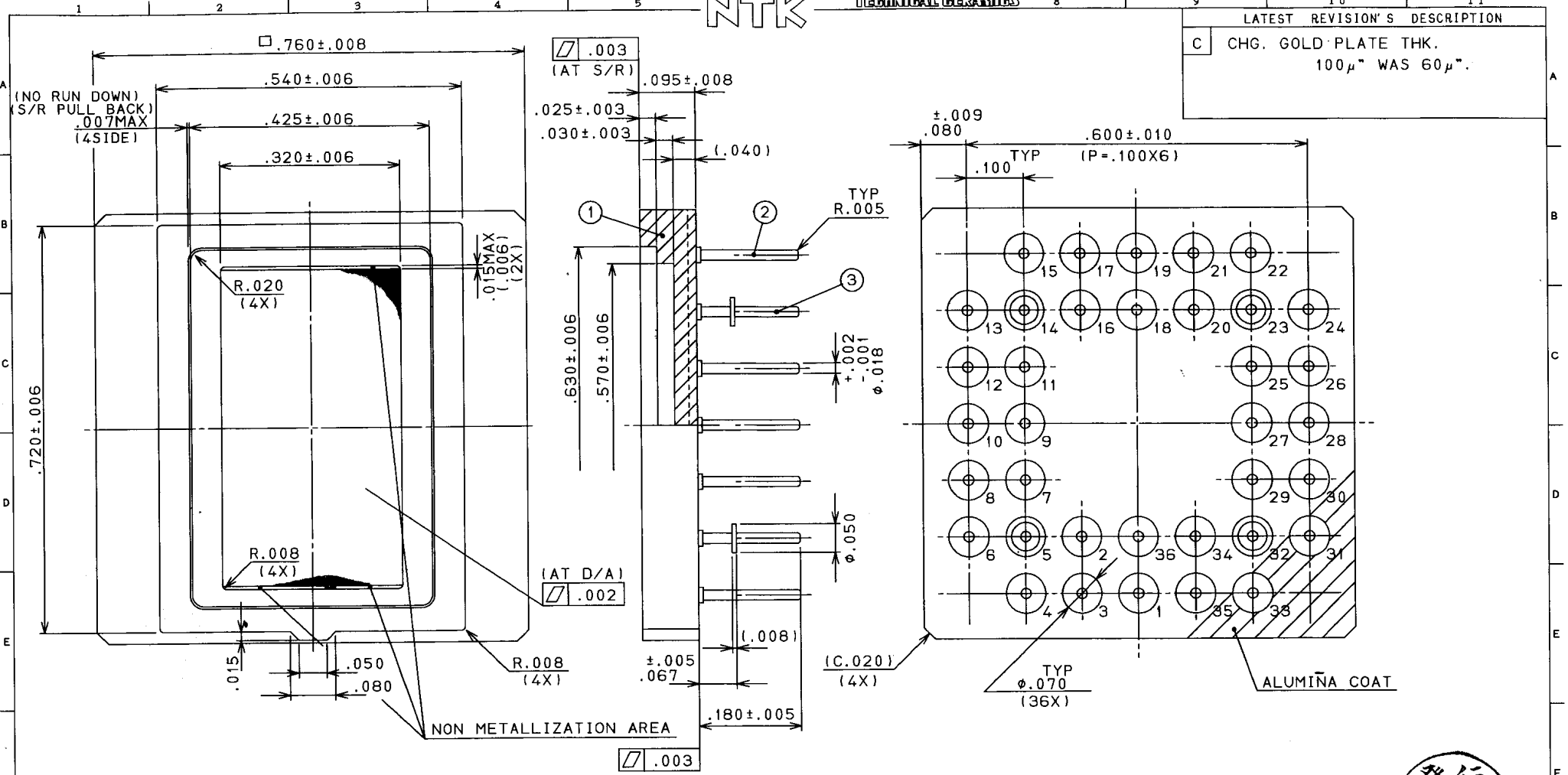


C CHG. GOLD PLATE THK.
100μ" WAS 60μ"



NOTES:

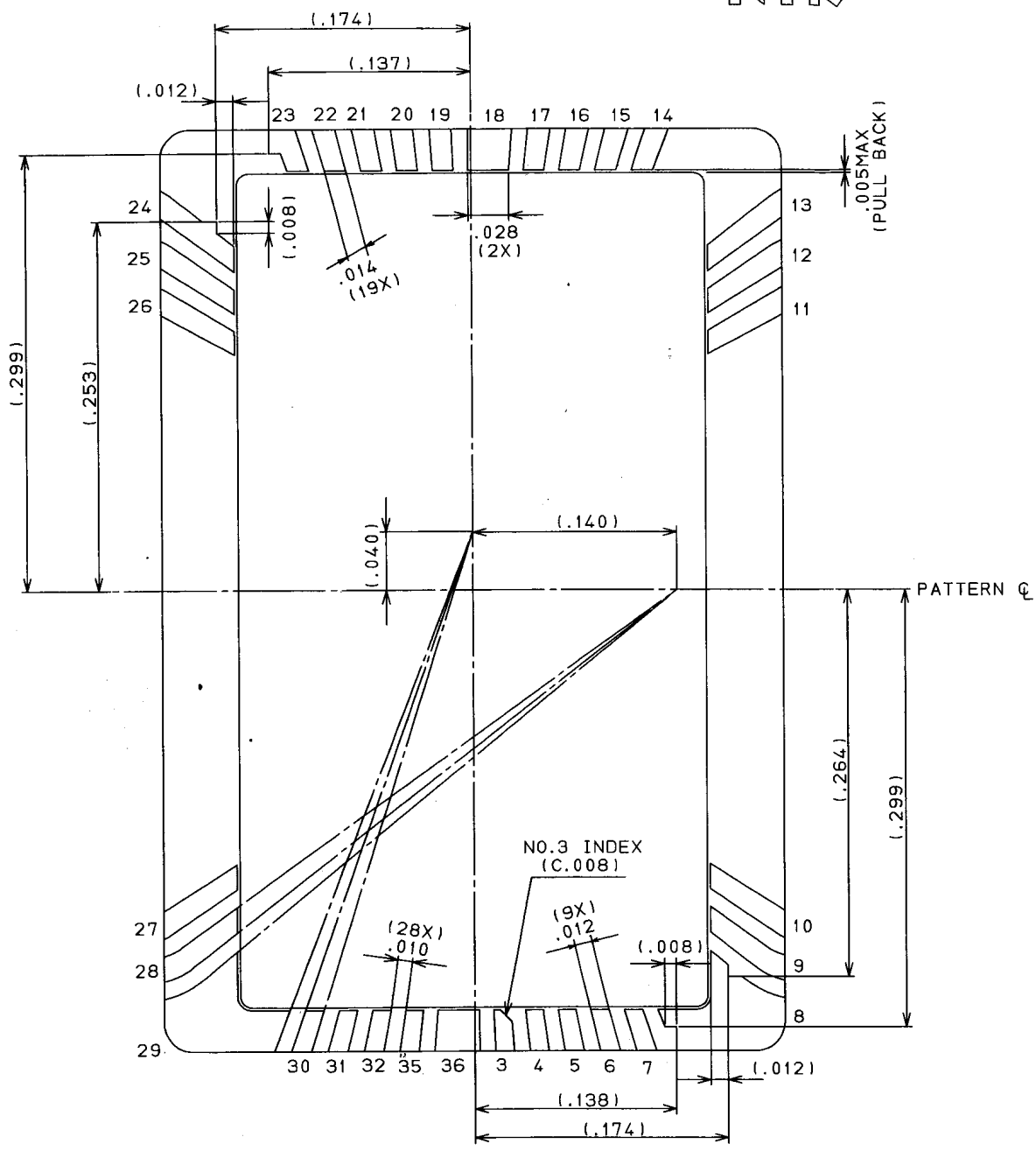
1. PLATING 100μ INCHES MIN GOLD OVER
50~350μ INCHES NICKEL.
2. LEAD RESISTANCE: 800mΩ MAX.
3. PAD NO.3 AND PIN NO.3 TO BE ELECTRICALLY
CONNECTED TO THE DIE ATTACH PAD.
SEAL RING ISOLATED.
4. PIN NO.1,2,33,34 SHALL BE ELECTRICALLY
ISOLATED.

REQUIRED TO MODIFY

Item	Name	Material	Description	Rev.	Description	Date
3	STAND OFF PIN	ALLOY42			C RE DRAWING	MAR-14-1999
2	PIN	ALLOY42			B RE DRAWING	MAR-12-1998
1	CERAMIC	BLACK ALUMINA			A RE DRAWING	MAR-31-1992
					φ NEW DRAWING	FEB-19-1992
UNLESS OTHERWISE SPECIFIED TOLERANCES: ± 1% N. L. T. 2 DECIMALS. XX ± 01 3 DECIMALS. XXX ± 005			DRAWN N.KAWAI	NTK TECHNICAL CERAMICS NGK SPARK PLUG CO., LTD		
CUSTOMER			CHECKED	TITLE (LARGE CAVITY SIZE)		
DWG NO.			APPROVED JW	36 PIN GRID ARRAY		
			UNIT INCH	DWG NO. IPK36F1-8907B		
			SCALE	SIZE A-2 (C)		

MODIFIED DWG NO.

A CHG. NTK DWG NO.
-8907B WAS -8907A.



REQUIRED TO MODIFY

MODIFIED DWG NO.	
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UNLESS OTHERWISE SPECIFIED TOLERANCES: ± 1%	DRAWN N. KAWAI	NTK TECHNICAL CERAMICS
N. L. T. 2 DECIMALS. XX ± .01	CHECKED	NGK SPARK PLUG CO., LTD
3 DECIMALS. XXX ± .005	APPROVED JW	TITLE B/G PADS DETAIL & CONNECTION TABLE
CUSTOMER	UNIT INCH	DWG NO. IPK36F1-8907B
DWG NO.	SCALE	SIZE A-2

Rev.	Description	Date
A	RE DRAWING	MAR-12-1996
φ	NEW DRAWING	FEB-19-1992